Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	ti.com/support
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	06/09/2022

### Details for "TLV7113318DDSET"

#### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLV7113318DDSET	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DSE   6	1.5x1.5x0.75	4.1

#### \*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

#### **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

### **Component Information**

Component	Substance	CAS Number		Homogeneous Material Level		Component Level	
			Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.0107	97.334668	973347	0.260424	2604
Precious Metals	Palladium	7440-05-3	0.000293	2.665332	26653	0.007131	71
Sub-Total			0.010993	100	1000000	0.267555	2676
Die Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.022119	30	300000	0.538347	5383
Other Inorganic Materials	Silica	7631-86-9	0.003318	4.500203	45002	0.080756	808
Other Organic Materials	Chlorine	7782-50-5	0.000026	0.035264	353	0.000633	6
Thermoplastics	Ероху	85954-11-6	0.048267	65.464533	654645	1.174754	11748
Sub-Total			0.07373	100	1000000	1.79449	17945
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	1.462995	97.533	975330	35.607343	356073
Copper and Its Alloys	Iron	7439-89-6	0.034755	2.317	23170	0.84589	8459
Copper and Its Alloys	Phosphorus	7723-14-0	0.000375	0.025	250	0.009127	91
Zinc and Its Alloys	Zinc	7440-66-6	0.001875	0.125	1250	0.045635	456
Sub-Total			1.5	100	1000000	36.507996	365080
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.09512	95.12	951200	2.315094	23151
Precious Metals	Gold	7440-57-5	0.00078	0.78	7800	0.018984	190
Precious Metals	Palladium	7440-05-3	0.0041	4.1	41000	0.099789	998
Sub-Total			0.1	100	1000000	2.433866	24339
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	1.787085	90.500026	905000	43.495261	434953
Other Plastics and Rubber	Carbon Black	1333-86-4	0.009873	0.49998	5000	0.240296	2403
Thermoplastics	Ероху	85954-11-6	0.177721	8.999994	90000	4.325492	43255
Sub-Total			1.974679	100	1000000	48.061048	480610
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.449287	100	1000000	10.935045	109350
Sub-Total			0.449287	100	1000000	10.935045	109350
Total			4.108689			100	1000000

### Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

## **Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

# **Product Content Methodology**

For an explanation of the methods used to determine material weights, See Product Content Methodology

# Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

## Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

## Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.